

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUC60N04S6L039	**Issued**	28. October 2019
MA#	MA001701320		
Package	PG-TDSON-8-33	**Weight***	111.25 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.285	0.26	0.26	2558	2558
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		143	
	non noble metal	iron	7439-89-6	0.053	0.05		476	
	non noble metal	copper	7440-50-8	52.842	47.49	47.55	475001	475620
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	400	400
encapsulation	organic material	carbon black	1333-86-4	0.077	0.07		694	
	plastics	epoxy resin	-	6.099	5.48		54827	
	inorganic material	silicondioxide	60676-86-0	32.427	29.15	34.70	291488	347009
leadfinish	non noble metal	tin	7440-31-5	1.574	1.41	1.41	14147	14147
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1881	1881
solder	non noble metal	tin	7440-31-5	0.009	0.01		83	
	noble metal	silver	7440-22-4	0.012	0.01		103	
	non noble metal	lead	7439-92-1	0.440	0.40	0.42	3951	4137
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.02		151	
	non noble metal	copper	7440-50-8	16.828	15.13	15.15	151265	151461
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
	non noble metal	copper	7440-50-8	0.310	0.28	0.28	2783	2787
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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